

line 9, delete

"BACKGROUND OF THE INVENTION" and insert therefor

- Description of the Background - .

Page 3, line 31, delete "EMBODIMENT" and insert therefor - -EMBODIMENTS- -.

IN THE CLAIMS

Claim 1, line 1, delete "Substrate" and insert therefor - -A substrate- -.

Claims 2-13, line, delete "Substrate" and insert therefor - -The substrate- -.

Claim 14, line 1, delete "Security" and insert therefor - -A security- -.

Claim 15, line 1, delete "Security" and insert therefor - -A security- -.

Claim 16, line 1, delete "Security" and insert therefor - -A security- -.

Claim 17, line 1, delete "Optically" and insert therefor - -An optically- -.

Please add the following new Claims:

- -18. The substrate according to Claim 1, which further comprises polyimide having polyaniline blocks thereon underneath said semiconductive organic polymer.
- 19. The substrate according to Claim 1, which further comprises an insulating layer on said semiconductive organic polymer.
- 20. The substrate according to Claim 1, having an uppermost layer of polyaniline.
- 21. The substrate according to Claim 1, wherein the paper has a thickness up to 100 μ m.
- 22. The security paper according to Claim 14, which is a banknote.
- 23. The security document according to Claim 15, which is a passport.
- 24. The security document according to Claim 15, which is an identity card.
- 25. The security document according to Claim 15, which is a security.- -